

APPLICATION PROFILE

NOTICE

THIS INFORMATION WILL BE USED BY CLEANLOGIX TO DETERMINE AN APPROPRIATE CLEANING METHOD OR PROCESS PRIOR TO COMMENCEMENT OF FIELD OR LABORATORY TESTING ACTIVITIES. THIS INFORMATION WILL NOT BE SHARED WITH A THIRD PARTY. PLEASE PROVIDE AS MUCH DETAIL AS POSSIBLE. AN APPLICATIONS ENGINEER WILL CONTACT YOU SHORTLY.

DATE:/	
a. COMPANY NAME:	
b. CONTACT NAME:	
c. E-MAIL:	
d. STREET ADDRESS:	
e. CITY:	
f. STATE/PROVINCE:	
g. POSTAL CODE:	
h. TELEPHONE NUMBER:	
i. WEBSITE:	
2. PRODUCT INFORMATION	
a. NAME OF PRODUCT:	
b. USE/PURPOSE:	
c. LENGTH:	
d. WIDTH:	
e. HEIGHT:	
f. DIAMETER:	

1.

GENERAL INFORMATION

g. UNIT WEIGH	T:					
h. MATERIALS OF CONSTRUCTION:						
3. PROCES	PROCESS INFORMATION					
a. IS YOUR PRODUCT CLEANED IN A CLEANROOM/ CONTROLLED ENVIRONMENT? Yes / No CLASS:						
b. WHAT IS THE PRODUCTION/ASSEMBLY OPERATION PRECEDING CLEANING?						
c. WHAT IS THE PRODUCTION OPERATION FOLLOWING CLEANING?						
d. HOW IS YOU	R PRODU	CT CLEANED?				
i. ii. iii. iv. v.	HAT ARE Y	OUR CURREN STEP 1: STEP 2: STEP 3: STEP 4: STEP 5:	T CLEANING	S PROCESS STEPS?		
f. CLEANING AGENT(S) USED: g. CLEANING FLUID TEMPERATURE: DEGREES C						
h. TYPE OF ENERGY USED:						
i. CLEAN PACKAGING REQUIRED? PLEASE SPECIFY:						
4. CONTAN	IINATES A	ND CLEANING	REQUIREM	ENTS		
a. KNOWN/MEASURED SURFACE CONTAMINANTS:						
h SOURCE OF	CONTAMI	NATION:				

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5.	PRODUCTION LOT / CLEANIN	G LOT II	NFORMATION				
a. V	WHAT THROUGHPUT IS REQUIRE	:D?					
b. V	WHAT IS THE PRODUCTION LOT	SIZE?					
	c. HOW IS YOUR PRODUCTION GROUPED? (i.e. all product from one machine per shift or from one assembler, etc.)						
d. H	HOW MANY LOTS PER DAY?						
e. II	IF DIFFERENT, WHAT IS THE CLE	ANING L	OT SIZE?				
f. A	ARE PARTS CLEANED ONE AT A T	IME? Y	ES / NO				
g. H	HOW OFTEN IS A BATCH CLEANE	D?					
h. ⊢	HOW MANY DIFFERENT PARTS W						
i. D	DO THEY ALL HAVE THE SAME CO						
•	S THERE ANY REASON THAT YOU PREVENTS THEM FROM BEING CL						
k. H	HOW ARE PARTS FIXTURED, IF A						
6.	POST CLEANING SURFACE T (i.e., PLASMA TREATMENT, F						
	DESCRIBE ANY POST-CLEANING REQUIRED FOR BONDING, COAT						
7.	. INSPECTION / SURFACE TRI	EATMEN	T VERIFICATION				
a. (. CLEANLINESS TEST METHODS/E	QUIPME	NT:				
b. I	IS INSPECTION: 100%?	YES	NO □				

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BASED ON SAMPLING PLAN? (PLEASE DESCRIBE)

8. AUTOMATION REQUIREMENTS (PLEASE DESCRIBE)

9. EQUIPMENT PURCHASE

- a. PLANNED PURCHASE/INSTALLATION DATE FOR NEW CLEANING EQUIPMENT:
- b. ARE YOU INTERESTED IN INTEGRATING CO₂ CLEANING INTO A PRODUCTION/ASSEMBLY TOOL? YES / NO
- c. ARE YOU INTERESTED IN AUTOMATING YOUR NEW CLEANING TOOL? YES / NO

10.ADDITIONAL INFORMATION

a. ARE THERE ANY SPECIAL CLEANING CHALLENGES SUCH AS SOFT COATINGS, MACHINING CHIPS, BLIND HOLES, ETC.? (PLEASE DESCRIBE)





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